L Number	Hits	Search Text	DB	Time stamp
1	2	("5,073,456").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/20 17:05
2	2	("6,242,079").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/20 17:05
-	0	"metal substrate" and adhesion and "interganular etch$4" and plat$4 and (immersion or immerse) near6 plating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:48
-	0	"metal substrate" and adhesion and "interganular etching" and plat$4 and (immersion or immerse) near6 plating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:46
-	0	"metal substrate" and adhesion and "interganular etch$4" and plat$4 and (immersion or immerse) and plating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:47
-	0	"metal substrate" and adhesion and "interganular etch$4" and plat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:47
-	0	"metal substrate" and adhesion and "interganular etch$4"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:48
-	0	"metal substrate" and adhesion and "intergranular etch$4" and plat$4 and (immersion or immerse) near6 plating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:48
-	0	"metal substrate" and adhesion and "intergranular etch$4" and plat$4 and (immersion or immerse) and plating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:49
-	0	"metal substrate" and adhesion and "intergranular etch$4" and plat$4 and (immersion or immerse or immers$4) and plating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:49
-	9	metal adj3 substrate and adhesion and intergranular adj1 etch$4 and plat$4 and immers$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:14
-	9	metal and adhesion and intergranular adj1 etch$4 and plat$4 and immers$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:15
-	13	metal and adhesion and intergranular near11 etch$4 and plat$4 and immers$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:17
-	28	intergranular and etch$4 and plat$4 and immers$4 and adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:31

–	0	intergranular and 216.34.ccls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:32
– ·	0	216.34.ccls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:32
–	1	216/34.ccls. and intergranular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:32
–	143	216/34.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:34
–	14	216/34.ccls. and metal and plate and adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:37
–	628	"adhesion promotion" and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:38
–	0	"adhesion promotion" and metal and intergranualr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:38
–	2	intergranualr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:39
–	4381	intergranular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:39
–	0	intergranular and "adhesion promotion" and metal and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:39
–	0	intergranular and adhesion and promotion and metal and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:40
–	3846	inter$12 and adhes$12 and promot$12 and meta$12 and etc$12	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:53
–	205	inter$12 and adhes$12 and promot$12 and meta$12 and etched	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:56
–	1318017	car andnot vehicle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:59

-	467135	intergranular andnot copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 12:00
-	3369	intergranular not copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 12:00
-	1011	intergranular and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 12:00
-	0	intergranular and adhesion near3 promotion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 12:09
-	1030	intergranular near3 etch or adhesion near3 promotion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 12:10
-	0	intergranular near3 etch and promotion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 12:10
-	0	intergranular near3 etch and adhere	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 12:11
-	6	intergranular and etch and adhere	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 13:13
-	118	"copper strike" and nickel and (iron ferrous ferric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 13:16
-	89	intergranular and etch$4 and plat$4 and immers$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 13:19
-	7	intergranular and etch$4 and plat$4 and immers$4 and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 14:15
-	0	("surface grain boundry" intergranular) and plate and etch and (copper nickel) and (immersion immerse) and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 14:18
-	53	("surface grain boundry" intergranular) and plate and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 15:54
-	1	"3265526".PN.	USPAT	2002/03/07 14:27
-	1	"3573100".PN.	USPAT	2002/03/07 14:31
-	1	"3632498".PN.	USPAT	2002/03/07 14:31
-	1	"3650861".PN.	USPAT	2002/03/07 14:34
-	1	"3706600".PN.	USPAT	2002/03/07 15:37
-	1	"3711385".PN.	USPAT	2002/03/07 15:37

-	1	"3778307".PN.	USPAT	2002/03/07 15:38
-	1	"3864163".PN.	USPAT	2002/03/07 15:39
-	1	"3878083".PN.	USPAT	2002/03/07 15:39
-	1	"3864163".PN.	USPAT	2002/03/07 15:40
-	1	"3878083".PN.	USPAT	2002/03/07 15:40
-	1	"3882002".PN.	USPAT	2002/03/07 15:40
-	1	"3948736".PN.	USPAT	2002/03/07 15:41
-	1	"3950240".PN.	USPAT	2002/03/07 15:42
-	1	"4005003".PN.	USPAT	2002/03/07 15:43
-	1	"4039400".PN.	USPAT	2002/03/07 15:44
-	1	"4068025".PN.	USPAT	2002/03/07 15:46
-	1	"4039400".PN.	USPAT	2002/03/07 15:50
-	1	"4068025".PN.	USPAT	2002/03/07 15:50
-	1	"4140813".PN.	USPAT	2002/03/07 15:51
-	1	"4140813".PN.	USPAT	2002/03/07 15:52
-	1	"4255247".PN.	USPAT	2002/03/07 15:53
-	1	"4272354".PN.	USPAT	2002/03/07 15:53
-	1	"4328080".PN.	USPAT	2002/03/07 15:53
-	1	"4331528".PN.	USPAT	2002/03/07 15:53
-	1	"4331528".PN.	USPAT	2002/03/07 15:54
-	35	("surface grain boundry" intergranular) and plate and etch and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 11:48
-	3	("5205473").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 11:59
-	1	"5092485".PN.	USPAT	2002/03/08 08:39
-	48	5205473.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 08:38
-	50	"5205473"	USPAT	2002/03/08 08:39
-	48	5205473.uref.	USPAT	2002/03/08 08:39
-	0	"99/40764"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:27
-	8	sadey	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:35
-	11	"5869130"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:52
-	54522	pcb intergranular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:52
-	10	pcb and intergranular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:56
-	368	(adhere adhesion) and intergranular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:56

–	18	(adhere adhesion) and intergranular and etch and (organic polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:04
–	500244	(adhere adhesion) mear promotion (intergranular "grain boundary") and etch and (organic polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:05
–	1173	(adhere adhesion) near promotion (intergranular "grain boundary") and etch and (organic polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:05
–	1173	(adhere adhesion) near1 promotion (intergranular "grain boundary") and etch and (organic polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:05
–	933	(adhere adhesion) near1 promotion (intergranular "grain boundary") near1 etch and (organic polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:06
–	923	(adhere adhesion) near1 promotion (intergranular "grain boundary") near1 etch and (organic polymer)and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:06
–	923	(adhere adhesion) near1 promotion (intergranular "grain boundary") near1 etch and (organic polymer) and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:06
–	0	(adhere adhesion) near1 promotion near1 (intergranular "grain boundary") near1 etch and (organic polymer) and "circuit board"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:07
–	0	(adhere adhesion) near1 promotion and (intergranular "grain boundary") near1 etch and (organic polymer) and "circuit board"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:07
–	2	(adhere adhesion) near1 promotion and (intergranular "grain boundary")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 13:11
–	0	"(adhere adhesion) near1 promotion".ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 11:00
–	58	"adhesion promotion".ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 15:11
–	1	"3508983".PN.	USPAT	2002/03/08 14:38
–	1	"3698940".PN.	USPAT	2002/03/08 14:38
–	1	"3698940".PN.	USPAT	2002/03/08 14:38
–	1	"3873499".PN.	USPAT	2002/03/08 14:38
–	1	"3978252".PN.	USPAT	2002/03/08 14:38
–	1	"4042729".PN.	USPAT	2002/03/08 14:38
–	1	"4100312".PN.	USPAT	2002/03/08 14:38
–	1	"4159222".PN.	USPAT	2002/03/08 14:38
–	1	"4499152".PN.	USPAT	2002/03/08 14:38
–	1	"4574031".PN.	USPAT	2002/03/08 14:38
–	1	"4897118".PN.	USPAT	2002/03/08 14:38

–	1	"4902556".PN.	USPAT	2002/03/08 14:38
–	1	"4976990".PN.	USPAT	2002/03/08 14:38
–	1	"5061550".PN.	USPAT	2002/03/08 14:38
–	1	"5071701".PN.	USPAT	2002/03/08 14:38
–	1	"5073456".PN.	USPAT	2002/03/08 14:38
–	1	"5153024".PN.	USPAT	2002/03/08 14:38
–	8	"intergranular etch" and adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 15:12
–	2	"boundary layer" near11 etch and adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 15:33
–	1	"4353954".PN.	USPAT	2002/03/08 15:14
–	112	metal near polymer near adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 16:12
–	1126	427/304.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 16:13
–	175	427/304.ccls. and adhesion and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 16:13
–	3466	bisphenol and plastic near11 can and coat$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 09:12
–	334	bisphenol and plastic near11 can and coat$ and food	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 09:24
–	198	(bisphenol or plastic or polymer) and "reinforcing bar" and coat$ and bridge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 10:12
–	1	"5372449".PN.	USPAT	2002/03/12 09:37
–	1	"5175032".PN.	USPAT	2002/03/12 09:37
–	1	(bisphenol or plastic or polymer) and "reinforcing bar" and coat$ and bridge and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 10:15
–	9	intergranular near3 etch and adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 10:41
–	0	intergranular near3 etch and adhesion AND PROMOT$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 10:43
–	926	(adhere adhesion) near1 promotion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 11:00

-	3	(adhere adhesion) near1 promotion and "copper strike" and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 11:06
-	5	(adhere adhesion) near1 promotion and "copper strike"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 11:41
-	0	"09/628036"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 11:41
-	14	"628036"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 11:41
-	2	("6036758").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:14
-	0	("wo 99/40764").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:14
-	0	"wo 99/40764"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:14
-	0	"99/40764"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:14
-	17	"40764"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:22
-	0	"40764" and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:15
-	0	("wo9940764").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:23
-	3	("9940764").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:23
-	0	wo009940764	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 12:24
-	0	wo9940764	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 15:00

-	0	wo009617975	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 15:00
-	0	wo9617975	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 15:01
-	0	"wo9617975"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 15:01
-	5	"9617975"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/12 16:26
-	8	"9619097"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 12:52
-	1	("copper strike" and adhesion).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 13:02
-	423	("intergranular" or "grain boundary" and adhesion).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 13:07
-	2	(("intergranular etch" or "grain boundary") and adhesion).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 13:10
-	1	JP03130142A	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 13:12
-	2	("grain boundary" or intergranular) and adhesion near5 promotion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 13:15
-	1231	("grain boundary" or intergranular) and adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 13:16
-	13	("grain boundary" or intergranular) near5 etch and adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 14:34
-	1	"4797182".PN.	USPAT	2002/03/13 13:22
-	19	("grain boundary" or intergranular or surface roughening) near5 etch near5 plating and adhesion near5 (enhanced enhance enhances enhancing improve improves improving improved)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 15:27
-	1	"6010768".PN.	USPAT	2002/03/13 15:08

-	2150	428/209.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 15:29
-	337	428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adhere adhesion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 15:31
-	1035949	428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adhere adhesion) (copper nickel tin silver bismuth gold cadmium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 15:33
-	310	428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/13 15:33
-	251	428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) and metal and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 10:50
-	3	("5800859").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 11:36
-	3	("3,650,861").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 12:13
-	5	("3,773,577").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 13:19
-	2	("6162503").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 13:22
-	2	("5,869,130").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 15:51
-	1	surfeel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 16:02
-	34	etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" and (sulfonic SO3H)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 16:11
-	1	etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/18 09:59
-	689	thiazole and "hydrogen peroxide" near10 acid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/18 10:01

–	3	thiazole and "hydrogen peroxide" near10 acid and "printed circuit board"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/18 10:02
–	3366	"aspect ratio" near3 "5"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 09:06
–	117	"aspect ratio" near3 "5" and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 09:07
–	3	"aspect ratio" near3 "5" and etch and grain and boundary	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 09:10
–	0	"aspect ratio$2" near3 "5" and etch and (grain or boundary)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 09:11
–	33	aspect near2 ratio$2 near3 "5" and etch and (grain or boundary)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 09:15
–	0	aspect near2 ratio$2 near3 etch near22 (grain or boundary)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 09:15
–	53	aspect near2 ratio$2 near3 etch and (grain or boundary)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 11:29
–	3	"40764" and phenyl	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 11:31
–	0	("wo9940764").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 11:31
–	3	("9940764").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 11:34
–	2	GRIESER.in. and HAUF.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 11:35
–	3	GRIESER.in. and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 11:35
–	209	GRIESER.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:44

-	3	GRIESER.in. and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:16
-	4	GRIESER.in. and meyer.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:17
-	10	"9900243"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:44
-	0	"de9900243"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:44
-	0	"de99/00243"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:44
-	0	(""de99/00243"").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:45
-	0	(""99/00243"").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:47
-	0	"is not identical to the sulfinic, selenic or tellurinic"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:49
-	0	"seleninic or tellurinic"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 13:03
-	55	"seleninic"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:57
-	0	("wo9940764").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:58
-	0	("WO9940764").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:58
-	0	WO009940764	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:58
-	3	"9940764"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 12:59

–	0	seleninic near3 tellurinic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 13:25
–	2144	formamidine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 13:25
–	323	"formamidine sulfinic acid"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 13:26
–	104	"formamidine sulfinic acid" and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 13:26
–	1	"formamidine sulfinic acid" and copper and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 14:34
–	3	("4882202").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:08
–	0	("surface.ti. rough$5.ti.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:10
–	652210	surface.ti. rough$5.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:10
–	63	selenic and telluric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:11
–	0	"selenic or telluric"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:21
–	0	"selenic near3 telluric"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:21
–	0	"selenic near4 telluric"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:21
–	0	"selenic near telluric"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:22
–	0	"selenic adj3 telluric"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:23

-	0	"selenic near45 telluric"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:23
-	0	selenic near4 telluric.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:23
-	0	selenic near3 telluric.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:24
-	0	selenic near2 telluric.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:24
-	0	selenic near1 telluric.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:24
-	0	selenic near telluric.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:24
-	0	selenic and telluric.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:27
-	55	seleninic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:24
-	0	seleninic and tellurinic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:25
-	12	tellurinic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:25
-	63	selenic and telluric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:27
-	40	selenic near4 telluric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:27
-	8	selenic near1 telluric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:34
-	297	"copper strike"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:35

–	216	"copper strike" and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:35
–	175	"copper strike" and nickel and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:35
–	43	"copper strike" near5 nickel and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:36
–	16	"copper strike" near5 nickel and electroplate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:48
–	2353362	roughen$4 and adhere adn plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:49
–	1976	roughen$4 and adhere and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 15:56
–	2	("6,036,758").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 16:08
–	3	("5,907,015").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 16:11
–	2	("5,807,493").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 16:19
–	2	("5,733,599").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 16:24
–	3	("5712047").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 16:41
–	3	("5,554,211").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 16:56
–	2	("5073456").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/19 17:12
–	3	("5017271").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/20 08:22

| | 3 | ("4642161").PN. | USPAT;
US-PGPUB;
EPO; JPO;
DERWENT;
IBM TDB | 2002/03/20 08:22 |